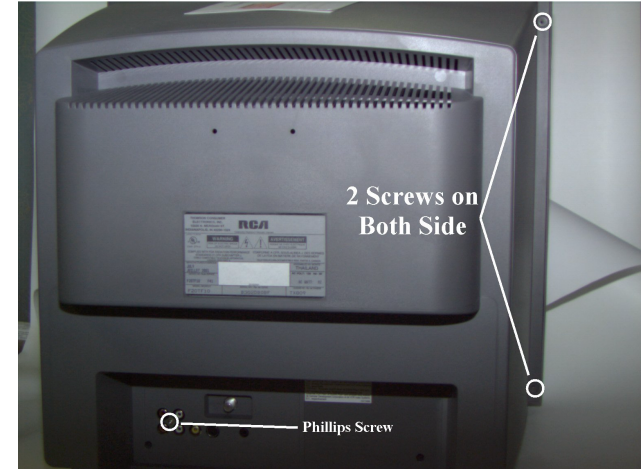


DISASSEMBLY PROCEDURES

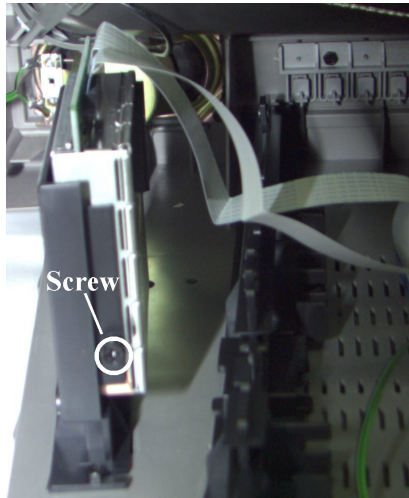
Back Cover Removal

- 1. Remove five screws to release the back cover. 2 from each side and a small Phillips screw located among the rear audio jacks.
- 2. Lift the back rear edge of the back cover and pull back to remove.



Gemstar Module Removal

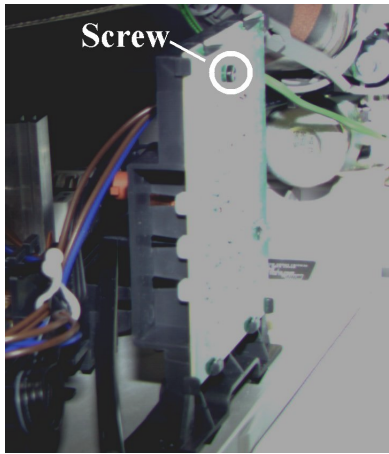
- 1. Remove the back cover.
- 2. Remove the small screw at the lower back edge of the plastic support.
- 3. Disconnect the 2 ribbon cables (BG403 & BG 404) from the top of the Gemstar PCB.
- 4. Lift the Gemstar module straight up and out.



E/W Correction Module Removal

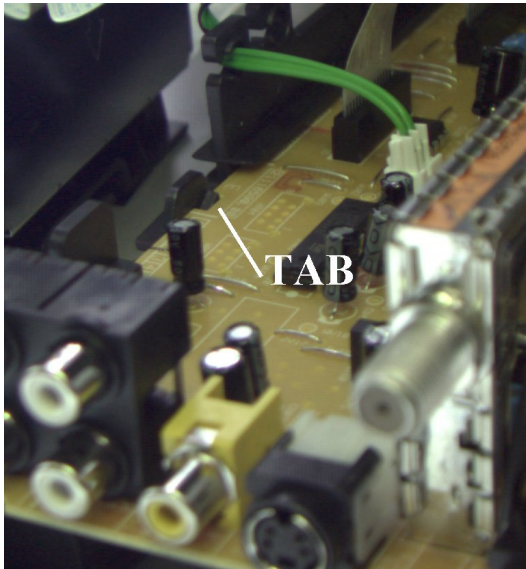
- 5. Remove the back cover.
- 6. Remove the small screw at the top center back of the PCB.
- 7. Disconnect the 2 cables (BL108 & BL103) from the E/W Correction PCB.

- 8. Raise the 2 tabs at the top of the plastic holder and pull the top of the PCB clear of the tabs. Lift the module straight up and out.



Main Chassis PCB Removal

- 9. Disconnect the AC power cable.
- 10. Remove the back cover.
- 11. Discharge the anode lead to the picture tube ground strap and remove the anode lead before disconnecting other cables.
- 12. Disconnect cable assemblies P1402, P3101, P3203, P3401 and P4010 from the Main PCB.



- 13. Push out on the plastic Tabs on either side of the tray and slide the chassis back and out until clear of the

CHIP COMPONENT REMOVAL

Replacement Procedure for Chip Removal

The following procedures are recommended for the replacement of the chip components used in this unit. Failure to follow these procedures may lead to damage to the copper traces and pads on the printed circuit boards.

- 1.Preparation for replacement
 - a. Soldering Iron: Use a pencil-type soldering iron using less than 30 watts.
 - b. Solder Type: Eutectic Solder, Tin 63%/Lead 37%, is recommended.
 - c. Soldering Time: Do not apply heat for more than 4 seconds.
 - d. Preheating: Chip capacitors must be preheated before installation. (130 degrees - 150 degrees C).

Note: Chip component must not be reused after removal. Excessive mechanical stress and rubbing of the component electrode must be avoided.

- 2. Removing the chip component (Fig. 2-3):
Grasp the chip component body with tweezers and alternately apply heat to both electrodes.

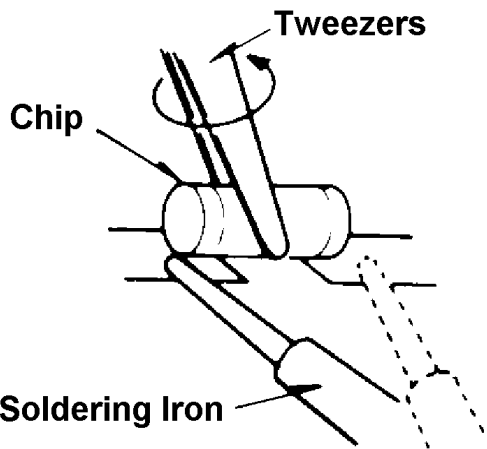


Figure 2-3, Removing Chip Components
When the solder on both electrodes has melted, remove the chip component with a twisting motion.

Note: Do not attempt to lift the component off the board until the component is completely disconnected from the board by a twisting action. *Attempting to remove the component before it has completely been disconnected can break the copper foil on the printed circuit board.*

- 3. Installing a chip component
 - a. Presolder the contact points on the circuit board (Fig. 2-4).

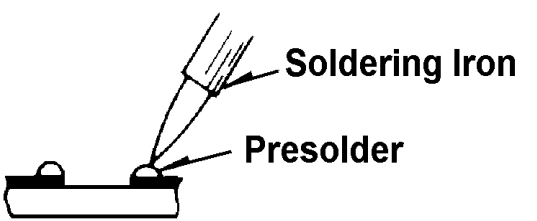


Fig.2-4, Chip Component Presolder

- b. Hold the component in position with tweezers and solder the electrodes as shown (Fig.2-3).

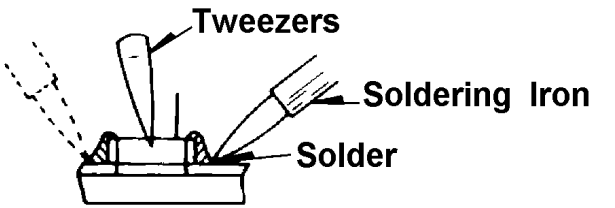


Fig. 2-3 - Chip Component Installation
Note: Do not glue the replacement chip component to the circuit board.